ABSTRACT

FORCED HEAT TRANSFER APPARATUS FOR HEATING STACKED DICE

An apparatus and method are provided for effectively heating a first die stacked above a second die attached onto a substrate during wire bonding conducted on the first die. A gas outlet positionable adjacent to the first die is configured to project a hot gas onto bond pads of the first die for bringing the bond pads to a desired bonding temperature, thereby rapidly heating the first die for effective wire bonding.

(FIG. 3)